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- Meets or Exceeds the Requirements of IOS 8802.3:1989 and ANSI/IEEE Std 802.3-1988
- Interdevice Loopback Paths for System Testing
- Squelch Function Implemented on the **Receiver Inputs**
- Drives a Balanced 78-Ω Load
- **Transformer Coupling Not Required in** System
- Power-Up/Power-Down Protection (Glitch
- **Isolated Ground Pins for Reduced Noise** Coupling
- **Fault-Condition Protection Built Into the** Device
- **Driver Inputs Are Level-Shifted ECL** Compatible
- **Package Options Include Plastic** Small-Outline (DW) Package and Standard Plastic (NT) DIP

(TOP VIEW) TXI1 24 TXO1 TXEN1 2 23 TXO1 LOOP1 3 22 🛮 V_{CC} GND 4 21 RXI1 RXEN1 5 20 | RXI1 RXO1 **1** 6 19 **∏** GND 18 | GND RXO2**∏** 7 RXEN2 8 17 | RXI2 16 RXI2 GND∏9 15 🛮 V_{CC} LOOP2 10 TXEN2 11 11 14 TXO2 13 TXO2 TXI2[] 12

DW OR NT PACKAGE

description

The SN75ALS085 is a high-speed, advanced low-power Schottky, dual-channel driver/receiver device designed for use in the AUI of ANSI/IEEE Std 802.3-1988. The two drivers on the device drive a 78- Ω balanced, terminated twisted-pair transmission line up to a maximum length of 50 meters. In the off (idle) state, the drivers maintain minimal differential output voltage on the twisted-pair line and, at the same time, remain within the required output common-mode range.

With the driver enable (TXEN) high, upon receiving the first falling edge into the driver input, the differential outputs rise to full-amplitude output levels within 25 ns. The output amplitude is maintained for the remainder of the packet. After the last positive packet edge is transmitted into the driver, the driver maintains a minimum of 70% full differential output for a minimum of 200 ns, then decays to a minimum level for the reset (idle) condition within 8 µs. Disabling the driver by taking the driver enable low also forces the output into the idle condition after the normal 8-us timeout. While operating, the drivers are able to withstand a set of fault conditions and not suffer damage due to the faults being applied. The drivers power up in the idle state to ensure that no activity is placed on the twisted-pair cable, which could be interpreted as network traffic.

The line receiver squelch function interfaces to a differential twisted-pair line terminated external to the device. The receiver squelch circuit allows differential receive signals to pass through, as long as the input amplitude and pulse duration are greater than the minimum squelch threshold. This ensures a good signal-to-noise ratio while the data path is active and prevents system noise from causing false data transitions during line shutdown and line-idle conditions. The receiver outputs (RXO) default to a high level and the receiver-enable (RXEN) outputs default to a low level while the squelch function is blocking the data path through the receiver (idle). The line receiver squelch becomes active within 50 ns when the input squelch threshold is exceeded. RXEN is driven high when the squelch circuit allows data to pass through the receiver. The receiver squelch circuit also can withstand a set of fault conditions while operating, without causing permanent damage to the device.



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description (continued)

The purpose of the loop functions is to provide a means by which system data-path verification can be done to isolate faulty interfaces and assist in network diagnosis. The LOOP pins are TTL compatible and must be held high for normal operation. When $\overline{\text{LOOP}}1$ is taken low, the output of driver 1 (TXO1) immediately goes into the idle state. Also, the input to receiver 1 is ignored, and a path from a transmit input (TXI1) to RXO1 is established. When $\overline{\text{LOOP}}1$ is taken back high, driver 1 and receiver 1 revert back to their normal operation. When $\overline{\text{LOOP}}2$ is taken low, a similar data path is established between TXI1 and RXO2. TXEN1 must be high for the loop functions to operate, and TXEN1 can be used to gate the loop function if desired. During loop operation, the respective RXEN reflects the status of TXEN1.

The SN75ALS085 is characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

	PACKAGED DEVICES					
TA	PLASTIC SMALL OUTLINE (DW)	PLASTIC DIP (NT)				
0°C to 70°C	SN75ALS085DW	SN75ALS085NT				

The DW package is available taped and reeled. Add the suffix R to device type (e.g., SN75ALS085DWR).

Function Tables

RECEIVER ($\overline{LOOP} = H$)

RXI	PREVIOUS	OUTPUTS		
KAI	RXEN	RXEN	RXO	
$V_{ID} = 1315 \text{ mV to } -175 \text{ mV},$	t _W < 25 ns	L	L	Н
$V_{ID} = -275 \text{ mV to } -1315 \text{ mV}$	$t_W > 50 \text{ ns}$	Х	Н	L
$V_{ID} = 318 \text{ mV to } 1315 \text{ mV},$	t _W < 142 ns	Н	Н	Н
$V_{ID} = 318 \text{ mV to } 1315 \text{ mV},$	t _W > 187 ns	Х	L	Н

H = high level, L = low level, X = don't care

DRIVER ($\overline{LOOP} = H$)

TXI	TXEN	PREVIOUS TXO	OUTPUT TXO
L	L	Idle	Idle
Н	L	Idle	Idle
\downarrow	Н	Idle	L
L	Н	Active	L
H < 260 μs	Н	Active	Н
H > 8 μs	Н	Active	Idle
L	L > 8 μs	Active	Idle
H < 260 ns	L > 8 μs	Active	Idle
H < 260 ns	L < 260 ns	Active	Н
H > 8 μs	L < 260 ns	Active	Idle
L	L < 260 ns	Active	L

 $H = V_I \geq V_T \; max, \; L = V_I \leq V_T \; min$



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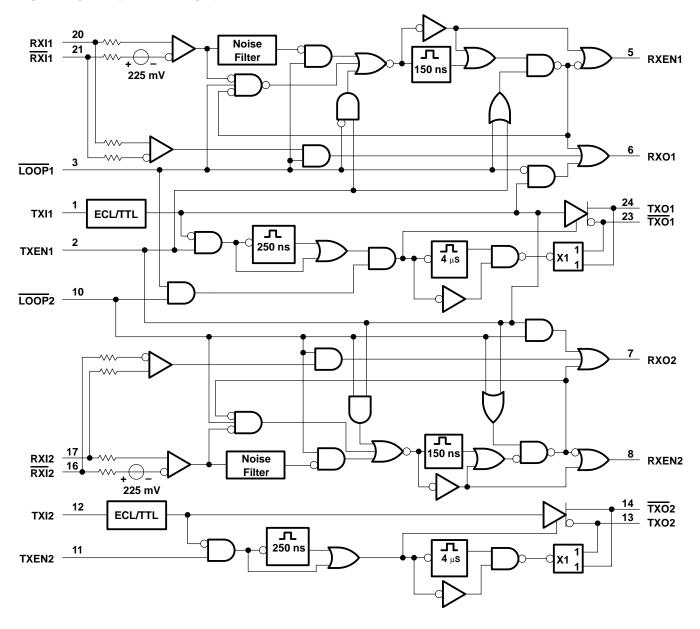
Function Tables (continued)

LOOP

	INPUTS						OUTPUTS			
LOOP1	LOOP2	TXI1	TXEN1	RXI1	RXI2	RXO1	RXO2	RXEN1	RXEN2	TXO1
L	L	L	Н	Х	Χ	L	L	Н	Н	Idle
L	L	Н	Н	Χ	Χ	Н	Н	Н	Н	Idle
L	L	Χ	L	Χ	Χ	Н	Н	L	L	Idle
L	Н	L	Н	Х	Normal	L	Normal	Н	Normal	Idle
L	Н	Н	Н	Χ	Normal	Н	Normal	Н	Normal	Idle
L	Н	Χ	L	Χ	Normal	Н	Normal	L	Normal	Idle
Н	L	L	Н	Normal	Х	Normal	L	Normal	Н	Idle
Н	L	Н	Н	Normal	Χ	Normal	Н	Normal	Н	Idle
Н	L	Χ	L	Normal	Χ	Normal	Н	Normal	L	Idle
Н	Н	Normal	Normal	Normal	Normal	Normal	Normal	Normal	Normal	Normal

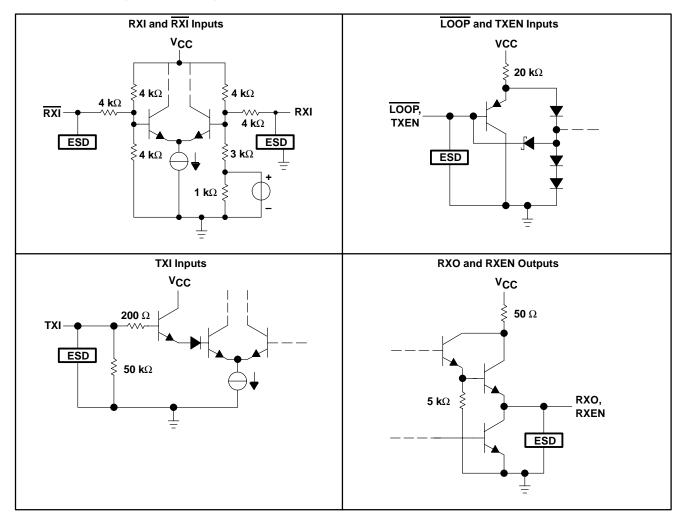
H = high level, L = low level, X = don't care

logic diagram (positive logic)





schematics of inputs and outputs



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	6 V
TXI and LOOP input voltage, V _I	5.5 V
TXO and TXO output voltage, VO	
RXI and $\overline{\text{RXI}}$ input voltage, V_1	
RXO and RXEN output voltage, VO	
Package thermal impedance, θ _{JA} (see Notes 2 and 3): DW package	
(see Notes 2 and 4): NT package	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{Stg}	–65 to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Voltage values are with respect to network ground terminal.

- 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.
- 4. The package thermal impedance is calculated in accordance with JESD 51-3.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.75	5	5.25	V
VIC	Common-mode voltage at RXI inputs	1		4.2	V
V_{ID}	Differential voltage between RXI inputs	±318		±1315	mV
V_{IH}	High-level input voltage, LOOP and TXEN	2			V
V _{IL}	Low-level input voltage, LOOP and TXEN			0.8	V
ЮН	High-level output current, RXO and RXEN			- 0.4	mA
loL	Low-level output voltage, RXO and RXEN			16	mA
t _{su1}	Setup time, driver mode, TXEN high before TXI↓ (see Figure 7)	10			ns
t _{su2}	Setup time, loop mode, LOOP low before TXEN↑ (see Figure 9)	15			ns
t _{su3}	Setup time, loop mode, TXEN high before TXI↓ (see Figure 9)	10			ns
t _{h1}	Hold time, loop mode, TXEN high after TXI↑ (see Figure 8)	10			ns
t _{h2}	Hold time, loop mode, LOOP low after TXEN↓ (see Figure 8)	15			ns
TA	Operating free-air temperature	0		70	°C



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electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER		TEST C	ONDITIONS	MIN	MAX	UNIT
۷ıK	Clamp voltage at all inputs		I _I = -18 mA			-1.5	V
				V _{CC} = 4.75 V	3.202	3.752	
			$T_A = 0$ °C	V _{CC} = 5 V	3.389	3.998	
				V _{CC} = 5.25 V	3.577	4.244	
				V _{CC} = 4.75 V	3.213	3.797	
V _(TO)	Driver input (TXI) threshold voltage		T _A = 25°C	V _{CC} = 5 V	3.400	4.043	V
` ´	,			V _{CC} = 5.25 V	3.588	4.289	
				V _{CC} = 4.75 V	3.239	3.849	
			T _A = 70°C	V _{CC} = 5 V	3.426	4.095	
				V _{CC} = 5.25 V	3.614	4.341	
	Receiver differential input threshold voltage					-275	mV
		Idle	TXEN at 0.8 V, LOOP2 at 2 V,	LOOP1 at 2 V, See Figure 1	1	4.2	
Voc	Driver output (TXO) common-mode voltage	Active	TXEN at 2 V, LOOP2 at 2 V, See Figure 1	LOOP1 at 2 V, TXI at 3.2 V,	1	4.2	V
		Active	TXEN at 2 V, LOOP2 at 2 V, See Figure 1	LOOP1 at 2 V, TXI at 4.4 V,	1	4.2	
		Idle	TXEN at 0.8 V, LOOP2 at 2 V,	LOOP1 at 2 V, See Figure 1		±40	
V _{OD}	Driver output (TXO) differential voltage	Active	TXEN at 2 V, LOOP2 at 2 V, See Figure 1	LOOP1 at 2 V, TXI at 3.2 V,	- 600	1315	mV
		Active	TXEN at 2 V, LOOP2 at 2 V, See Figure 1	LOOP1 at 2 V, TXI at 4.4 V,	600	1315	
Vон	High-level output voltage	RXO, RXEN	$I_{OH} = -0.4 \text{ mA}$		2.4		V
VOL	Low-level output voltage	RXO, RXEN	I _{OL} = 16 mA			0.5	V
		TXEN, LOOP	V _I = 2 V			20	
۱н	High-level input current	TXI	V _I = 4.5 V			400	μΑ
		RXI, RXI	$V_{ID} = -0.5 V$,	V _{IC} = 1 V to 4.2 V		1000	
		TXEN, LOOP	V _I = 0.8 V			-200	
l	Low-level input current	TXI	V _I = 3.1 V			100	^
¹IL	Low-level input current	171	V _I = 0.3 V		4	10	μΑ
		RXI, RXI	$V_{ID} = 0.5 V$,	V _{IC} = 1 V to 4.2 V		1000	
lod	Driver differential output current	Idle	TXEN at 0.8 V, LOOP2 at 2 V,	LOOP1 at 2 V, See Figure 2		±4	mA
los	Short-circuit output current [†]	RXO, RXEN	V _O at 0 V, RXI at 2 V	RXI at 3 V,	- 40	- 150	mA
Icc	Supply current		LOOP2 at 2 V, TXI at 4.5 V,	TXEN at 2 V, Outputs open		225	mA

[†] Not more than one output should be shorted at a time, and the duration of the test should not exceed 1 second.



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electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

PARAMETER		TEST CO	NDITIONS	MIN	MAX	UNIT
	TXO shorted to TXO,	Current measu	red in short		150	
	TXO at 0 V,	TXO is open,	Current measured at TXO		150	
	TXO is open,	TXO at 0,	Current measured at TXO		150	
Driver fault condition current‡	TXO at 0 V,	TXO at 0 V,	Current measured at TXO and TXO		150	mA
	TXO at 16 V,	TXO is open,	Current measured at TXO		150	
	TXO is open,	TXO at 16 V,	Current measured at TXO		150	
	TXO at 16 V,	TXO at 16 V,	Current measured at TXO and TXO		150	
	RXI shorted to RXI,	Current measu	red in short		10	
	RXI at 0 V,	RXI is open,	Current measured at RXI		3	
	RXI is open,	RXI at 0 V,	Current measured at RXI		3	
Receiver fault condition current‡	RXI at 0 V,	RXI at 0 V,	Current measured at RXI and RXI		3	mA
	RXI at 16 V,	RXI at open,	Current measured at RXI		10	
	RXI at open,	RXI at 16 V,	Current measured at RXI		10	
	RXI at 16 V,	RXI at 16 V,	Current measured at RXI and RXI		10	

[‡] Fault conditions should be measured on only one channel at a time.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

driver

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	MAX	UNIT
^t PLH	Propagation delay time, low-to-high level output	TXI	TXO, TXO	TXEN at 2 V,	See Figure 3		15	ns
^t PHL	Propagation delay time, high-to-low level output	TXI	TXO, TXO	TXEN at 2 V,	See Figure 3		15	ns
tPIL	Propagation delay time, idle-to-low level output	TXI	TXO, TXO	TXEN at 2 V,	See Figure 4		25	ns
tPIL	Propagation delay time, idle-to-low level output	TXEN	TXO, TXO	TXI at 3.2 V,	See Figure 5		25	ns
t _W	Output pulse duration, from low-to-high level to 70% output level		TXO, TXO	TXEN at 2 V,	See Figure 6	260	8000	ns
V _{OD(U)}	Driver output differential undershoot voltage	TXI	TXO, TXO	TXEN at 2 V,	See Figure 6		-100	mV
^t sk	Driver caused signal skew tPLH - tPHL	TXI	TXO, TXO	TXEN at 2 V,	See Figure 3		±3	ns
t _r	Rise time, TXO, TXO			TXEN at 2 V,	See Figure 3	1	5	ns
t _f	Fall time, TXO, TXO			TXEN at 2 V,	See Figure 3	1	5	ns

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receiver

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
tPLH	Propagation delay time, low-to-high level output	RXI, RXI	RXO	V _{IC} = 1 V to 4.2 V, See Figure 10		15	ns
tPHL	Propagation delay time, high-to-low level output	RXI, RXI	RXO	V _{IC} = 1 V to 4.2 V, See Figure 10		15	ns
^t PLH	Start-up delay time, low-to-high level output	RXI, RXI	RXEN	$V_{IC} = 1 \text{ V to } 4.2 \text{ V}, V_{ID} = -500 \text{ mV},$ See Figure 12		55	ns
tPHL	Shutdown delay time, high-to-low level output	RXI, RXI	RXEN	V_{IC} = 1 V to 4.2 V, V_{ID} = 500 mV, See Figure 12	142	181	ns
t _{sk}	Receiver caused signal skew (tpLH - tpHL)	RXI, RXI	RXO	V_{IC} = 1 V to 4.2 V, V_{ID} = 500 mV, See Figure 10		±3	ns
t _W	Pulse duration at RXI and RXI (to not activate squelch)			$V_{IC} = 1 \text{ V to } 4.2 \text{ V}, V_{ID} = -175 \text{ mV},$ See Figure 11	25		ns
t _W	Pulse duration at RXI and RXI (to activate squelch)			$V_{IC} = 1 \text{ V to } 4.2 \text{ V}, V_{ID} = -275 \text{ mV},$ See Figure 11		50	ns
t _{r1}	Rise time, RXO			V_{IC} = 1 V to 4.2 V, V_{ID} = ±500 mV, See Figure 10	1	8	ns
t _{r2}	Rise time, RXEN			V_{IC} = 1 V to 4.2 V, V_{ID} = ±500 mV, See Figure 12	1	8	ns
t _{f1}	Fall time, RXO			V_{IC} = 1 V to 4.2 V, V_{ID} = ±500 mV, See Figure 10	1	8	ns
t _{f2}	Fall time, RXEN			V_{IC} = 2.5 V, V_{ID} = ±500 V, See Figure 12	1	8	ns
t _V	RXO valid after RXEN high			See Figure 10	-10	15	ns

loop

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	MAX	UNIT
^t PLH	Propagation delay time, low-to-high level output	TXI	RXO	LOOP at 0.8 V, TXEN at 2 V, See Figure 13			30	ns
^t PHL	Propagation delay time, high-to-low level output	TXI	RXO	LOOP at 0.8 V, TXEN at 2 V, See Figure 13			30	ns
tPLH	Propagation delay time, low-to-high level output	TXEN	RXEN	LOOP at 0.8 V, See Figure 14			50	ns
^t PHL	Propagation delay time, high-to-low level output	TXEN	RXEN	LOOP at 0.8 V, See Figure 14			50	ns

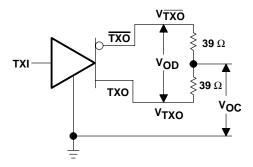


Figure 1. Driver Test Circuit

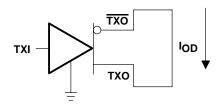


Figure 2. Driver Test Circuit

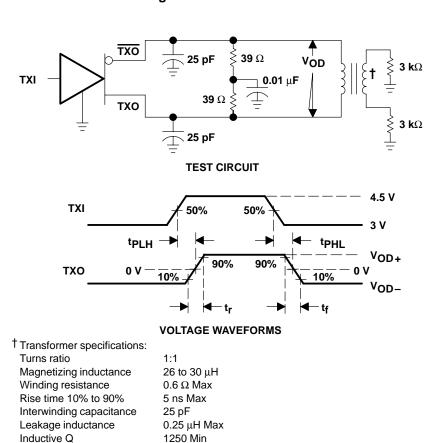
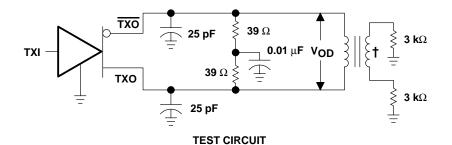
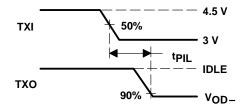


Figure 3. Test Circuit and Voltage Waveforms





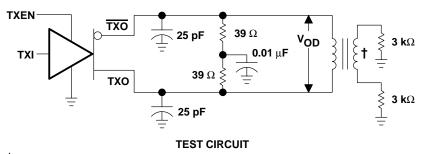
† See Figure 3



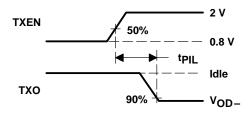
VOLTAGE WAVEFORMS

NOTE A: Input $t_{\Gamma} \le 5$ ns; $t_{f} \le 5$ ns

Figure 4. Test Circuit and Voltage Waveforms

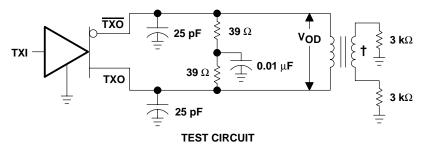


† See Figure 3



VOLTAGE WAVEFORMS

Figure 5. Test Circuit and Voltage Waveforms



† See Figure 3

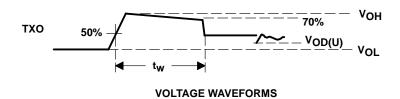


Figure 6. Test Circuit and Voltage Waveforms

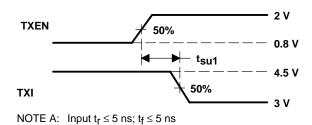
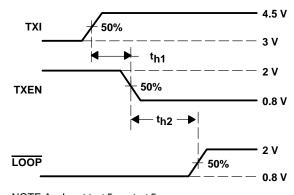


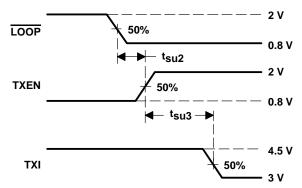
Figure 7



NOTE A: Input $t_f \le 5$ ns; $t_f \le 5$ ns

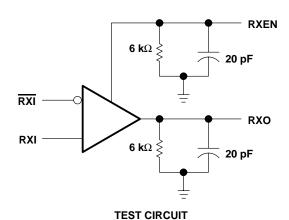
Figure 8

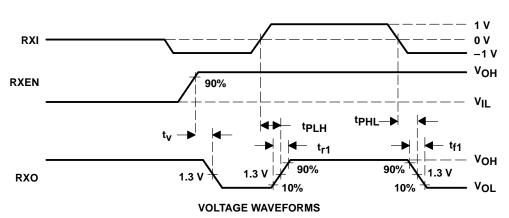




NOTE A: Input $t_r \le 5$ ns; $t_f \le 5$ ns

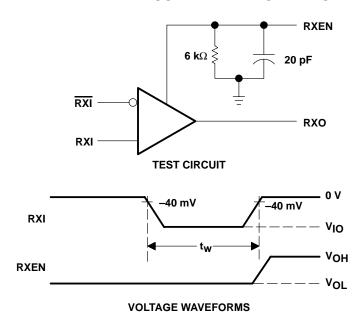
Figure 9





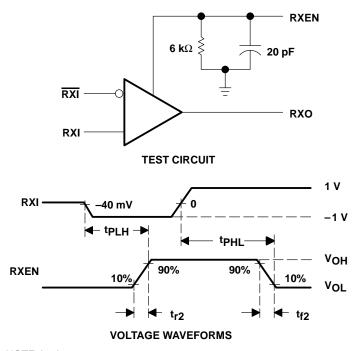
NOTE A: Input $t_{f} \le 5$ ns; $t_{f} \le 5$ ns

Figure 10. Test Circuit and Voltage Waveforms



NOTE A: Input $t_{f} \le 5$ ns; $t_{f} \le 5$ ns

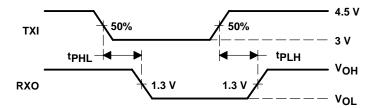
Figure 11. Test Circuit and Voltage Waveforms



NOTE A: Input $t_{\Gamma} \le 5$ ns; $t_{f} \le 5$ ns

Figure 12. Test Circuit and Voltage Waveforms





NOTE A: Input $t_{\Gamma} \le 5$ ns; $t_{f} \le 5$ ns

Figure 13

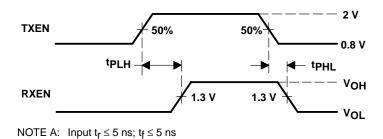


Figure 14

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